Product iQ®

Wiring, Printed - Component

COMPANY
ELTEK LTD
SEGULA INDUSTRIAL ZONE
PO BOX 159
PETACH-TIKVA, 49101 Israel

E51098

Type	Cond Width Min mm	Min Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Assembly Solder Process Cycles	Solder Limits °C	Solder Limits sec	Max Oper Temp °C	Flame Class	Meets UL796 DSR	C T I
Multilayer printed wiring boards															
1	0.10	0.30	34 Int:68	DS	31.75	No	-	-	-	260	20	105	V-0	All	*
1-1	0.10	0.08	8.5 Int:68	DS	31.75	No	-	-	-	260	20	105	V-0	All	3
2	0.05	0.15	8.5 Int:68	DS	31.75	No	-	-	-	288	30	130	V-0	All	3
3	0.05	0.15	8.5 Int:68	DS	31.75	No	-	-	-	288	30	130	V-0	All	4
4 (ASP 1)	0.05	0.15	8.5 Int:68	DS	31.75	Yes	Yes	260	6	288	30	130	V-0	All	3
Multilayer printed wiring boards made from prefabricated type (mass laminated) industrial laminates															
1	0.10	0.3	33	DS	31.8	No	-	-	-	260	20	105	V-0	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions, flammability only Recognition															
EK	-	-	-	DS	-	No	-	-	-	288	30	-	V-0	-	-
EK1	-	-	-	DS	-	No	-	-	-	288	30	-	V-0	-	-
Single layer printed wiring boards															
1A	0.10	0.30	34	DS	31.75	No	-	-	-	260	20	105	V-0	All	-
1A-1	0.10	0.08	8.5	DS	31.75	No	-	-	-	260	20	105	V-0	All	-
2A	0.05	0.15	8.5	DS	31.75	No	-	-	-	288	30	130	V-0	All	-
3A	0.05	0.15	8.5	DS	31.75	No	-	-	-	288	30	130	V-0	All	-
4A (ASP 1)	0.05	0.15	8.5	DS	31.75	Yes	Yes	260	6	288	30	130	V-0	All	3

* - CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or tradename "EK", "EL" or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2026-05-04